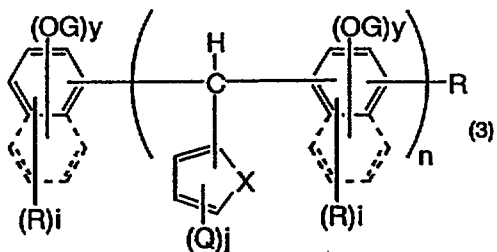
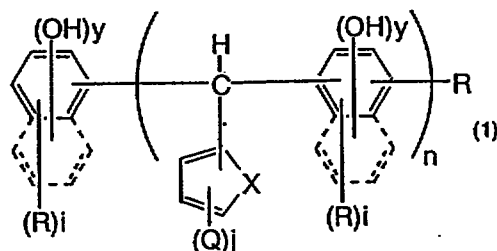


ABSTRACTS

Resin compositions having a low viscosity, a low hygroscopicity, high adhesive properties and a high heat resistance as well as being light in weight and excellent in mechanical properties are provided. The resin compositions include polyhydric phenol compounds represented by the formula (1) and epoxy resins represented by the formula (3).



This Sheet Has Been Replaced



THIS SHEET HAS BEEN
REPLACED